



Material Content Data Sheet



Sales Product Name	BSO033N03MS G			Issued		23. January 2020		
MA#	MA005400457							
Package	PG-DSO-8-39			Weight*		84.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.944	3.50	3.50	35021	35021
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		122	
	non noble metal	zinc	7440-66-6	0.041	0.05		487	
	non noble metal	iron	7439-89-6	0.820	0.97		9749	
	non noble metal	copper	7440-50-8	33.276	39.58	40.61	395842	406200
wire	non noble metal	copper	7440-50-8	0.321	0.38	0.38	3816	3816
encapsulation	organic material	carbon black	1333-86-4	0.225	0.27		2672	
	plastics	epoxy resin	-	6.963	8.28		82831	
	inorganic material	silicondioxide	60676-86-0	37.735	44.90	53.45	448889	534392
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9681	9681
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	863	863
glue	plastics	epoxy resin	-	0.126	0.15		1504	
	noble metal	silver	7440-22-4	0.717	0.85	1.00	8523	10027
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com